

102b is stated at column 4, line 40, to be a side wall. The undersigned has been unable to note where a stabilizer is provided in Mosely et al. of the type claimed as noted above. Furthermore, nothing in Mosley et al. relates to or is concerned with leadframe lead planarity, this being a principal purpose of the present invention. Accordingly, if the Examiner persists in this rejection, he is requested to particularly point out.

In addition, Mosley et al. relates to totally non-analogous art. Mosley et al. relates to a die carrier and the structure to which the Examiner refers relates to die carrier structure. This structure of Mosley et al. has nothing whatsoever to do with the problem and the solution thereof of the subject application. In particular, Mosley et al. is not a stabilizer for leadframe leads and has no relation to such a device.

Claim 2 further limits claim 1 by requiring that the stabilizer be made of an insulating material. No such combination is taught or suggested by Mosley et al.

Claim 5 further limits claim 1 by requiring that the die pad mount have a recess in one surface into which a semiconductor die is mounted. It is respectfully submitted that Mosely et al. does not teach or suggest this feature either alone or in the combination as claimed. In this way, for example, a semiconductor die can be disposed on the die mount and, due to the recess, still have its top surface coplanar with or even below the leadframe leads to allow easy connection between die pads on the die and leadframe leads.

Claim 6 contains the features discussed above with reference to claim 1 and therefore defines over Mosely et al. for at least the reasons set forth above with reference to Mosely et al.

Claim 6 further requires a semiconductor die mounted in the recess. No such feature is taught or suggested by Mosely et al. either alone or in the combination as claimed.

Claim 7 depends from claim 6 and therefore defines patentably over Mosely et al. for at least the reasons presented above with reference to claim 6.

Claim 7 further limits claim 6 by requiring that the stabilizer be made of an insulating material. No such combination is taught or suggested by Mosely.

Claim 10 relates to a method and requires adhering a stabilizer along part of the length and on each side of the leadframe leads and forming a die pad integral with the stabilizer and disposed beneath the central semiconductor die-receiving region to improve leadframe planarity. No such method is taught or suggested by Mosely et al. As stated above, leadframe lead planarity is not even a consideration of Mosely et al. The arguments present above with reference to claim 1 are also incorporated herein by reference.

Claim 11 and 12 depend from claim 10 and therefore define over Mosely et al. for at least the reasons presented above with reference to claim 10.

In addition, claim 11 further limits claim 10 by requiring the step of forming a recessed area in the die pad for mounting of a semiconductor die therein. No such step is taught or suggested by Mosely et al. either alone or in the combination as claimed.

Claim 12 further limits claim 10 by requiring that the stabilizer be made of an insulating material. No such combination is taught or suggested by Mosely et al.

Claim 1 was rejected under 35 U.S.C. 102(b) as being anticipated by Suzuki et al. The rejection is respectfully traversed.

Note in Suzuki et al. that the element 112 is a part of the leadframe itself and not a die pad mount integral with and forming a part of said stabilizer disposed beneath the central semiconductor die-receiving region for retaining a semiconductor die thereon.

Claims 3, 4, 8, 9, 13 and 14 were rejected under 35 U.S.C. 103(a) as being unpatentable over Mosley et al. in view of Kitahara (U.S. 5,568,363). The rejection is respectfully traversed.

Claims 3 and 4 depend from claim 1, claims 8 and 9 depend from claim 6 and claims 13 and 14 depend from claim 10 and therefore define over Mosely et al. in view of Kitahara for at least the reasons presented above with reference to the claims from which they depend since Kitahara does not overcome the deficiencies in Mosely et al. noted above.

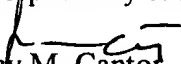
In addition, claims 3, 8 and 13 further limit claims 1, 6 and 10 by requiring that the stabilizer be made of plastic material. No such combination is taught or suggested by Mosely, Kitahara or any proper combination of these patents.

Claims 4, 9 and 14 further limit claim 1, 6 and 10 by requiring that the stabilizer be made of a plastic material. No such combination is taught or suggested by Mosely, Kitahara or any proper combination of these patents.

Attached hereto is a proposed drawing correction. Approval is requested.

In view of the above remarks, favorable reconsideration and allowance are respectfully requested.

Respectfully submitted,


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